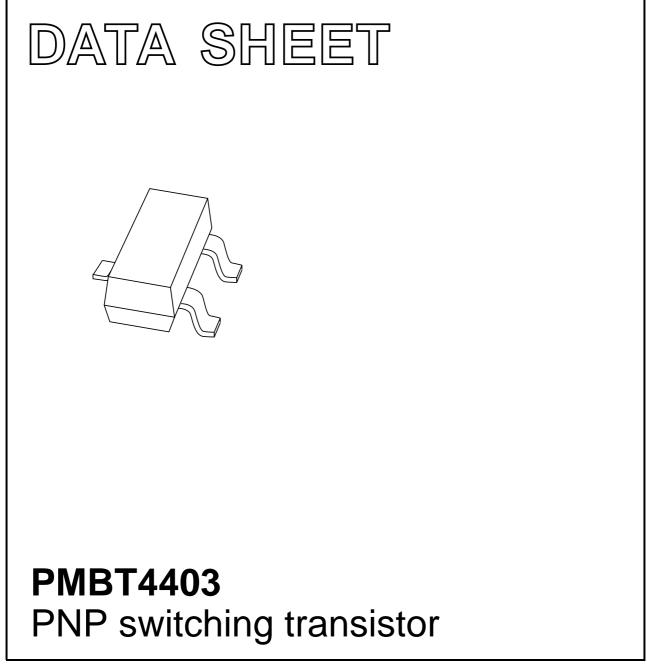
DISCRETE SEMICONDUCTORS



Product data sheet Supersedes data of 1999 Apr 15 2004 Jan 21



Product data sheet

PMBT4403

PNP switching transistor

FEATURES

- High current (max. 600 mA)
- Low voltage (max. 40 V).

APPLICATIONS

• Industrial and consumer switching applications.

DESCRIPTION

PNP switching transistor in a SOT23 plastic package. NPN complement: PMBT4401.

MARKING

TYPE NUMBER	MARKING CODE ⁽¹⁾	
PMBT4403	*2T	

Note

- 1. * = p: Made in Hong Kong.
 - * = t : Made in Malaysia.

* = W : Made in China.

ORDERING INFORMATION

TYPE	PACKAGE		
NUMBER	NAME	DESCRIPTION	VERSION
PMBT4403	_	plastic surface mounted package; 3 leads	SOT23

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	-	-40	V
V _{CEO}	collector-emitter voltage	open base	-	-40	V
V _{EBO}	emitter-base voltage	open collector	-	-5	V
I _C	collector current (DC)		-	-600	mA
I _{CM}	peak collector current		-	-800	mA
I _{BM}	peak base current		-	-200	mA
P _{tot}	total power dissipation	$T_{amb} \le 25 \ ^{\circ}C$; note 1	-	250	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Note

1. Transistor mounted on an FR4 printed-circuit board.

PIN	DESCRIPTION	
1	base	
2	emitter	
3	collector	

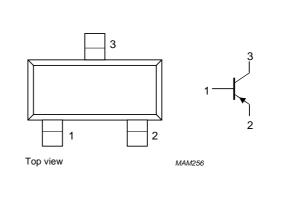


Fig.1 Simplified outline (SOT23) and symbol.

PNP switching transistor

PMBT4403

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	note 1	500	K/W

Note

1. Transistor mounted on an FR4 printed-circuit board.

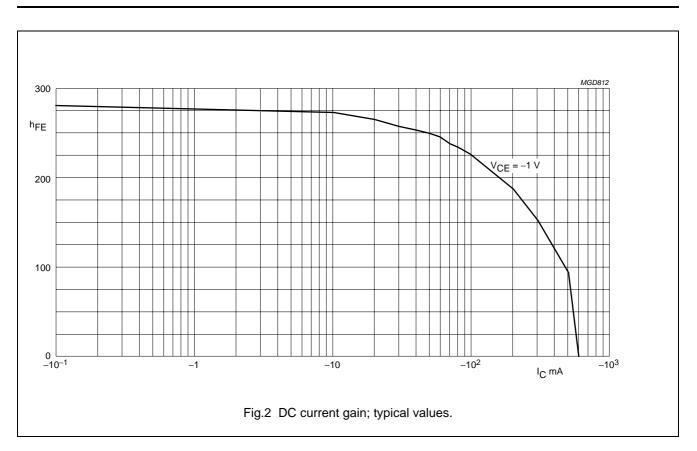
CHARACTERISTICS

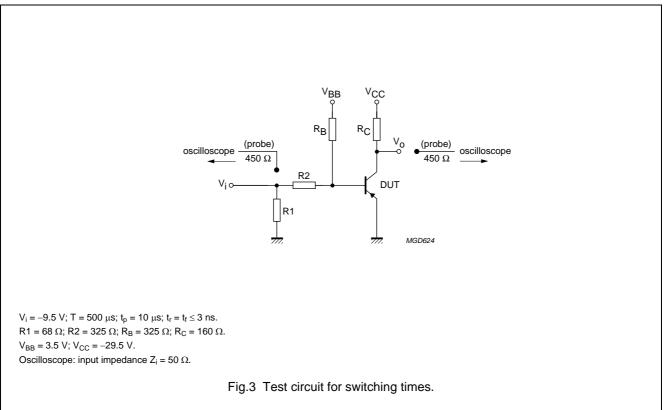
 T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I _{CBO}	collector-base cut-off current	$I_E = 0; V_{CB} = -40 V$	_	-50	nA
I _{EBO}	emitter-base cut-off current	$I_{C} = 0; V_{EB} = -5 V$	-	-50	nA
h _{FE}	DC current gain	V _{CE} = -1 V; (see Fig.2)			
		$I_{\rm C} = -0.1 {\rm mA}$	30	-	
		$I_{\rm C} = -1 \rm{mA}$	60	-	
		I _C = -10 mA	100	-	
		$V_{CE} = -2 V$			
		I _C = -150 mA	100	300	
		I _C = -500 mA	20	-	
OLOUI	collector-emitter saturation	I _C = -150 mA; I _B = -15 mA	_	-400	mV
	voltage	$I_{\rm C} = -500 \text{ mA}; I_{\rm B} = -50 \text{ mA}$	-	-750	mV
V _{BEsat}	base-emitter saturation voltage	I _C = -150 mA; I _B = -15 mA	_	-950	mV
		$I_{\rm C} = -500 \text{ mA}; I_{\rm B} = -50 \text{ mA}$	_	-1.3	V
C _c	collector capacitance	I _E = I _e = 0; V _{CB} = -10 V; f = 1 MHz	-	8.5	pF
Ce	emitter capacitance	$I_{C} = I_{c} = 0$; $V_{EB} = -500 \text{ mV}$; f = 1 MHz	_	35	pF
f _T	transition frequency	$I_{C} = -20 \text{ mA}; V_{CE} = -10 \text{ V}; f = 100 \text{ MHz}$	200	_	MHz
Switching t	imes (between 10% and 90% leve	els); (see Fig.3)			
t _{on}	turn-on time	I _{Con} = -150 mA; I _{Bon} = -15 mA;	_	40	ns
t _d	delay time	$I_{Boff} = 15 \text{ mA}$	_	15	ns
t _r	rise time		-	30	ns
t _{off}	turn-off time	1	_	350	ns
ts	storage time	1	_	300	ns
t _f	fall time	1	_	50	ns

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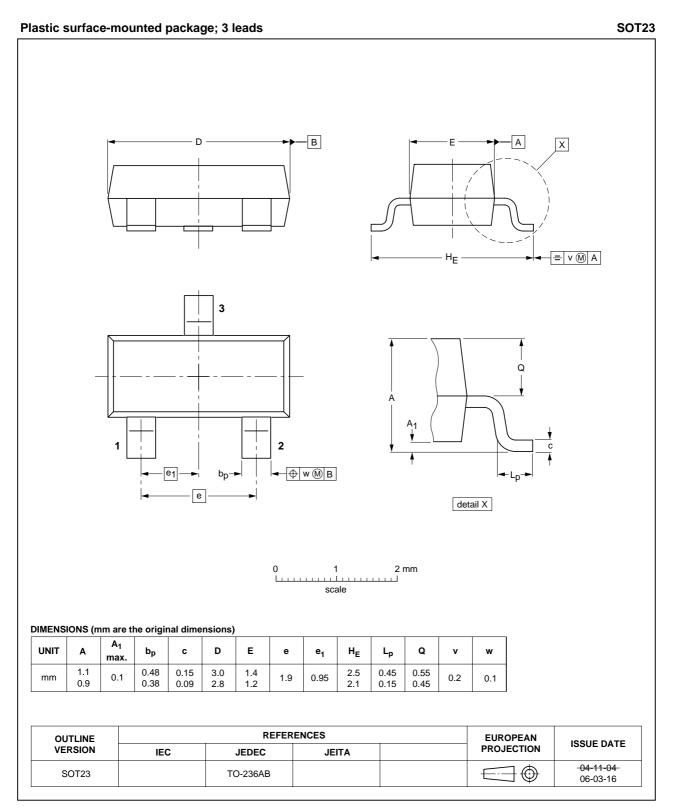
PNP switching transistor





PNP switching transistor

PACKAGE OUTLINE



PMBT4403

PNP switching transistor

PMBT4403

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

For additional information please visit: http://www.nxp.com For sales offices addresses send e-mail to: salesaddresses@nxp.com

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